

# LMP91200 Configurable AFE for Low-Power Chemical Sensing Applications

Check for Samples: [LMP91200](#)

## FEATURES

- Programmable output current in temperature measurement
- Programmable Output common mode voltage
- Active guarding
- On board sensor test
- Supported by Webench Sensor AFE Designer
- Supported by Webench Sensor Designer Tools

## APPLICATIONS

- pH sensor platforms

## KEY SPECIFICATIONS

Unless otherwise noted, typical values at  $T_A = 25^\circ\text{C}$ ,  $V_S = (V_{DD} - GND) = 3.3\text{V}$ .

- pH Buffer Input bias current ( $0 < V_{INP} < 3.3\text{V}$ )
  - max @  $25^\circ\text{C} \pm 125\text{ fA}$
  - max @  $85^\circ\text{C} \pm 445\text{ fA}$
- pH Buffer Input bias current ( $-500\text{mV} < V_{INP} - V_{CM} < 500\text{mV}$ ),  $V_S = (V_{DD} - GND) = 0\text{V}$ 
  - max @  $25^\circ\text{C} \pm 600\text{ fA}$
  - max @  $85^\circ\text{C} \pm 6.5\text{ pA}$
- pH Buffer Input offset voltage  $\pm 200\text{ }\mu\text{V}$
- pH Buffer Input offset voltage drift  $\pm 2.5\text{ }\mu\text{V}/^\circ\text{C}$
- Supply current (pH mode)  $50\text{ }\mu\text{A}$
- Supply voltage  $1.8\text{ V}$  to  $5.5\text{ V}$
- Operating temperature range  $-40^\circ\text{C}$  to  $125^\circ\text{C}$
- Package 16-Pin

## DESCRIPTION

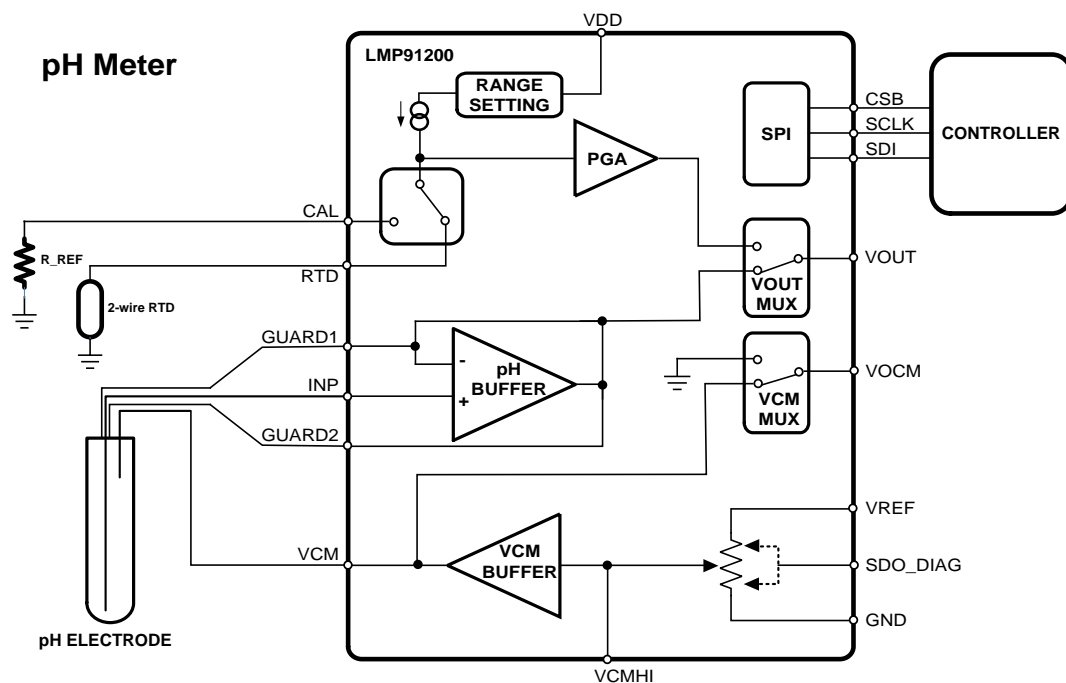
The LMP91200 is a configurable sensor AFE for use in low power analytical sensing applications. The LMP91200 is designed for 2-electrode sensors. This device provides all of the functionality needed to detect changes based on a delta voltage at the sensor. Optimized for low-power applications, the LMP91200 works over a voltage range of  $1.8\text{V}$  to  $5.5\text{V}$ . With its extremely low input bias current it is optimized for use with pH sensors. Also in absence of supply voltage the very low input bias current reduces degradation of the pH probe when connected to the LMP91200. The Common Mode Output pin (VOCM) provides a common mode offset, which can be programmed to different values to accommodate pH sensor output ranges. For applications requiring a high impedance common mode this option is also available. Two guard pins provide support for high parasitic impedance wiring. Support for an external Pt1000, Pt100, or similar temperature sensor is integrated in the LMP91200. The control of this feature is available through the SPI interface. Additionally, a user controlled sensor diagnostic test is available. This function tests the sensor for proper connection and functionality. Depending on the configuration, total current consumption for the device is  $50\text{ }\mu\text{A}$  while measuring pH. Available in a 16-pin TSSOP package, the LMP91200 operates from  $-40^\circ\text{C}$  to  $+125^\circ\text{C}$ .



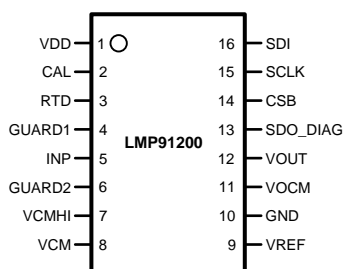
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**pH Meter**



## 16-Pin



### Figure 1. Top View

## Pin Functions

### Pin Descriptions

Pin	Name	Description
1	VDD	Positive Power Supply
2	CAL	Connect an external precision resistor here for purpose of temperature measurement calibration
3	RTD	Pt100/Pt1000 input / internal current source output
4	GUARD1	Active guard pin
5	INP	Non-inverting analog input of pH buffer
6	GUARD2	Active guard pin
7	VCMHI	High Impedance Programmable Common Mode output
8	VCM	Buffered Programmable Common Mode output
9	VREF	Voltage reference input
10	GND	Analog ground
11	VOCM	Output common mode voltage
12	VOUT	Analog Output
13	SDO_DIAG	Serial Data Out /Diagnostic enable
14	CSB	Chip select, low active.
15	SCLK	Serial Clock
16	SDI	Serial Data In



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## Absolute Maximum Ratings <sup>(1)</sup>

ESD Tolerance <sup>(2)</sup>	
Human Body Model	2000V
Machine Model	150V
Charge Device Model	1000V
Supply Voltage ( $V_S = V_{DD-GND}$ )	-0.3V to 6.0V
Voltage between any two pins	-0.3V to $V_{DD}+0.3V$
Current out at any pin	5mA
Storage Temperature Range	-65°C to 150°C
Junction Temperature <sup>(3)</sup>	+150°C
For soldering specifications:	
see product folder at <a href="http://www.ti.com">www.ti.com</a> and	
<a href="http://www.ti.com/lit/an/snoa549c/snoa549c.pdf">www.ti.com/lit/an/snoa549c/snoa549c.pdf</a>	

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics Tables.
- (2) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (3) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$ . All numbers apply for packages soldered directly onto a PC Board.

## Operating Ratings <sup>(1)</sup>

Supply Voltage ( $V_S = V_{DD-GND}$ )	1.8V to 5.5V
Temperature Range	-40°C to 125°C
Package Thermal Resistance ( $\theta_{JA}$ ) <sup>(2)</sup>	
16-Pin TSSOP	31°C/W

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics Tables.
- (2) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$ . All numbers apply for packages soldered directly onto a PC Board.

## Electrical Characteristics <sup>(1)(2)(3)</sup>

Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ .  $V_S = (V_{DD} - GND) = 3.3\text{V}$ .  $V_{REF} = 3.3\text{V}$ . Boldface limits apply at the temperature extremes.

Symbol	Parameter	Condition	Min (4)	Typ (5)	Max (4)	Units
Power supply						
Is	Supply Current (6) (7)	pH measurement mode		50	54 59	μA
		Temperature measurement mode, ICS=100uA		300	325 330	
		Temperature measurement mode, ICS=200uA		400	432 437	
		Temperature measurement mode, ICS=1000uA		350	364 372	
		Temperature measurement mode, ICS=2000uA		470	477 477	
pH Buffer						
AolpH	Open loop Gain	INP=1.65V 300mV=VOUT=VDD-300mV;	90	120		dB
VospH	Input Voltage Offset (6)	INP=1/8VREF	-200 -350		200 350	μV
		INP=7/8VREF	-200 -350		200 350	
TcVospH	Input offset voltage drift (8) (9)	INP=1/8VREF	-2.5		2.5	uV/°C
		INP=7/8VREF	-2.5		2.5	
VOSpH_drift	Long term VOSpH drift (10)	500 hours OPL		150		μV
IbpH	Input bias current at INP (9)	0V<INP<3.3V	-125		125	fA
		0V<INP<3.3V, 85°C	-445		445	fA
		0V<INP<3.3V, 125°C	-1.5		1.5	pA
		-500mV<(INP-VCM)<500mV, VS=0V.	-600		600	fA
		-500mV<(INP-VCM)<500mV, 85°C, VS=0V.	-6.5		6.5	pA
		-500mV<(INP-VCM)<500mV, 125°C, VS=0V.	-100		100	pA
GBWPpH	Gain Bandwidth Product (9)	CL=10pF, RL=1Mohm		220		KHz
CMRRpH	DC_Common mode rejection ratio	1/8VREF<INP<7/8VREF	80			dB
PSRRpH	DC_Power supply rejection ratio	1.8V<VDD<5V INP=1/8VREF	80			dB
		1.8V<VDD<5V INP=7/8VREF	80			

- (1) Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that  $T_J = T_A$ . No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where  $T_J > T_A$ .
- (2) Positive current corresponds to current flowing into the device.
- (3) The voltage on any pin should not exceed 6V relative to any other pins.
- (4) Limits are 100% production tested at  $25^\circ\text{C}$ . Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (5) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (6) Boldface limits are production tested at  $125^\circ\text{C}$ . Limits are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (7) Excluding all currents which flows out from the device.
- (8) Offset voltage average drift is determined by dividing the change in  $V_{OS}$  at the temperature extremes by the total temperature change.
- (9) This parameter is guaranteed by design and/or characterization and is not tested in production.
- (10) Offset voltage long term drift is determined by dividing the change in  $V_{OS}$  at time extremes of OPL procedure by the length of the OPL procedure. OPL procedure: 500 hours at  $150^\circ\text{C}$  are equivalent to about 15 years.

**Electrical Characteristics <sup>(1)(2)(3)</sup> (continued)**

Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ .  $V_S = (V_{DD} - GND) = 3.3\text{V}$ .  $V_{REF} = 3.3\text{V}$ . Boldface limits apply at the temperature extremes.

Symbol	Parameter	Condition	Min (4)	Typ (5)	Max (4)	Units
En_RMS <sub>pH</sub>	Input referred noise (low frequency) (9)	Integrated 0.1Hz to 10Hz		2.6		μV <sub>PP</sub>
en <sub>pH</sub>	Input referred noise (high frequency) (9)	f=1kHz		90		nV/ √Hz
Isc <sub>pH</sub>	Output short circuit current (11)	Sourcing, Vout to GND INP=1.65V	10	13		mA
		Sinking, Vout to VDD INP=1.65V	8	12		mA
VCM Buffer						
VCMHI_acc	VCMHI accuracy		-1.6		1.6	mV
Tc_VCMHI	VCMHI temperature coefficient (12) (9)	-40°C<T <sub>A</sub> <125°C	-18	-5	8	μV/°C
VCMHI_acc_VREF	VCMHI_acc vs. VREF (13) (9)	1.8V<VREF<5.0V	-500	-100	300	μV/V
Rout <sub>VCMHI</sub>	VCMHI Output Impedance (9)	VCMHI=1/2 VREF		250		KΩ
Aol <sub>VCM</sub>	Open loop Gain (6)	VCMHI=1/2 VREF, 300mV<VCM<VDD-300mV;	90	120		dB
Vos <sub>VCM</sub>	(VCM-VCMHI) (6)	VCMHI=1/8 VREF	-200 -350		200 350	μV
		VCMHI=7/8 VREF	-200 -350		200 350	
TcVos <sub>VCM</sub>	Input offset voltage drift ot (VCM-VCMHI) (8) (9)	VCMHI=1/8 VREF	-2.5		2.5	μV/°C
		VCMHI=7/8 VREF	-2.5		2.5	
Zout <sub>VCM</sub>	Output Impedance (14)	f=1KHz		4		Ω
PSRR <sub>VCM</sub>	DC_Power supply rejection ratio	1.8V<VDD<5V, VCMHI=1/8VREF	80			dB
		1.8V<VDD<5V, VCMHI=7/8VREF	80			
En_RMS <sub>VCM</sub>	Input referred noise (low frequency) (14)	Integrated 0.1Hz to 10Hz		2.6		μV <sub>PP</sub>
en <sub>VCM</sub>	Input referred noise (high frequency) (14)	f=1KHz		90		nV/ √Hz
Isc <sub>VCM</sub>	Output short circuit current (15)	Sourcing, Vout to GND VCMHI=1/2VREF	10	16		mA
		Sinking, Vout to VDD VCMHI=1/2VREF	8	12		
Current Source						
Ics	Current Source I <sub>CAL</sub> , I <sub>RTD</sub>	Programmable current		100 200 1000 2000		μA

(11) The short circuit test is a momentary open loop test.

(12) VCMHI voltage average drift is determined by dividing the change in VCMHI at the temperature extremes by the total temperature change.

(13) VCMHI\_acc vs. VREF is determined by dividing the change in VCMHI\_acc at the VREF extremes by the total VREF change.

(14) This parameter is guaranteed by design and/or characterization and is not tested in production.

(15) The short circuit test is a momentary open loop test.

**Electrical Characteristics <sup>(1)(2)(3)</sup> (continued)**

Unless otherwise specified, all limits guaranteed for  $T_A = 25^\circ\text{C}$ .  $V_S = (V_{DD} - GND) = 3.3\text{V}$ .  $V_{REF} = 3.3\text{V}$ . Boldface limits apply at the temperature extremes.

Symbol	Parameter	Condition	Min (4)	Typ (5)	Max (4)	Units
In_RMS <sub>CS</sub>	Input referred noise (low frequency) (14)	Integrated 0.1Hz to 10Hz		33		nA <sub>PP</sub>
in <sub>CS</sub>	Input referred noise (high frequency) (14)	f=1KHz		120		pA/ √Hz
Tcl <sub>CS</sub>	Current Source drift <sup>(16)</sup> (14)		-200	±35	200	ppm/°C
I_acc <sub>CS</sub>	Current Source accuracy		-2.5	1	2.5	%
PGA						
Vo <sub>S</sub> PGA	Input Voltage Offset (17)	+IN_PGA (Internal node) = 500mV	-275 -480		275 480	μV
TcVo <sub>S</sub> PGA	Input offset voltage drift (18) (14)	+IN_PGA (Internal node) = 500mV	-2.5		2.5	uV/°C
Aol <sub>PGA</sub>	Open loop Gain	+IN_PGA (Internal node) = 500mV	90	120		dB
AV <sub>PGA</sub>	Gain	Programmable gain		5 10		V/V
AV_acc <sub>PGA</sub>	Gain accuracy		-1.3		1.3	%
En_RMS <sub>PGA</sub>	Input referred noise (low frequency) (14)	Integrated 0.1Hz to 10Hz		2.6		μV <sub>PP</sub>
en <sub>PGA</sub>	Input referred noise (high frequency) (14)	f=1KHz		90		nV/ √Hz
PSRR <sub>PGA</sub>	DC_Power supply rejection ratio	1.8V<VDD<5V, +IN_PGA (Internal node) = 500mV	80			dB
Isc <sub>PGA</sub>	Output short circuit current (19)	Sourcing, Vout to GND +IN_PGA (Internal node) = 500mV	10	16		mA
		Sinking, Vout to VDD +IN_PGA (Internal node) = 500mV	8	12		
Reference Input						
Rin <sub>VREF</sub>	Input impedance (20)			500		KΩ

(16) Current source drift is determined by dividing the change in  $I_{CS}$  at the temperature extremes by the total temperature change.

(17) Boldface limits are production tested at 125°C. Limits are guaranteed through correlations using the Statistical Quality Control (SQC) method.

(18) Offset voltage average drift is determined by dividing the change in  $V_{OS}$  at the temperature extremes by the total temperature change.

(19) The short circuit test is a momentary open loop test.

(20) This parameter is guaranteed by design and/or characterization and is not tested in production.

## Electrical Characteristics (Serial Interface) <sup>(1)</sup>

Unless otherwise specified. All limits guaranteed for  $T_A=25^{\circ}\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ .

Symbol	Parameter	Condition	Min (2)	Typ (3)	Max (2)	Units
<b>VIL</b>	Logic Low Threshold				0.3XVDD	V
<b>VIH</b>	Logic High Threshold (SDO pin)		0.7XVDD			V
<b>VOL</b>	Output Logic LOW Threshold (SDO pin)	ISDO=100 $\mu$ A			0.2	V
		ISDO=2mA			0.4	
<b>VOH</b>	Output Logic High Threshold	ISDO=100 $\mu$ A	VDD-0.2			V
		ISDO=2mA	VDD-0.4			
<b>t1</b>	High Period, SCLK	(4)	100			ns
<b>t2</b>	Low Period, SCLK	(4)	100			ns
<b>t3</b>	Set Up Time, CSB to SCLK	(4)	50			ns
<b>t4</b>	Set Up Time, SDI to SCLK	(4)	30			ns
<b>t5</b>	Hold Time, S CLK to SDI	(4)	10			ns
<b>t6</b>	Hold Time, SCLK to SDO_DIAG	(4)	40			ns
<b>t7</b>	Hold Time, SCLK Transition to CSB Rising Edge	(4)	50			ns
<b>t8</b>	CSB Inactive	(4)	50			ns
<b>t9</b>	Hold Time, SCLK Transition to CSB Falling Edge	(4)	10			ns
<b>t<sub>R</sub>/t<sub>F</sub></b>	SDO_DIAG Signal Rise and Fall Times	Diagnostic disabled (5) (4)		30		ns

- (1) Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that  $T_J = T_A$ . No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where  $T_J > T_A$ .
- (2) Limits are 100% production tested at  $25^{\circ}\text{C}$ . Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (4) Load for these tests is shown in the timing diagram test circuit.
- (5) This parameter is guaranteed by design and/or characterization and is not tested in production.

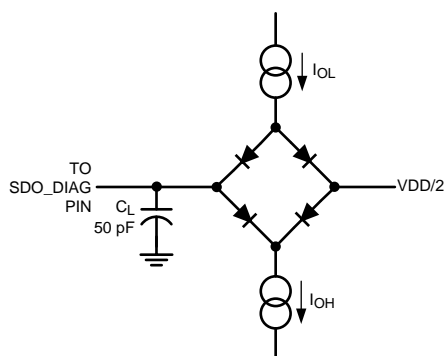
## Electrical Characteristics (Diagnostic) <sup>(1)</sup>

Unless otherwise specified. All limits guaranteed for  $T_A=25^{\circ}\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ .

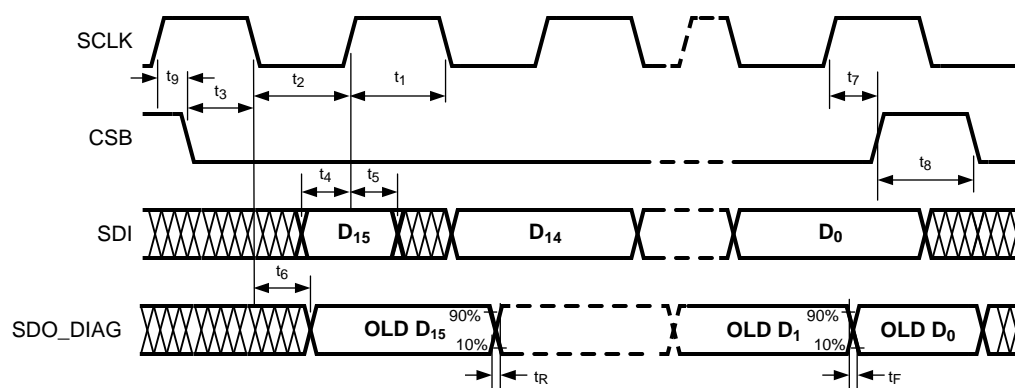
Symbol	Parameter	Condition	Min (2)	Typ (3)	Max (2)	Units
<b>DIAG_t<sub>SET</sub></b>	SDO_DIAG setup time (4)			200		ns
<b>DIAG_t<sub>R</sub>/DIAG_t<sub>F</sub></b>	Diagnostic Rise and Fall Times (Signal at SDO_DIAG pin, in Diagnostic Mode) (4)			30		ns
<b>DIAG_t<sub>ON</sub></b>	Minimum t <sub>ON</sub> of the diagnostic pulse at SDO_DIAG pin in Diagnostic Mode (4)			100		ns
<b>VCM_DIAG<sub>POS</sub></b>	Positive Diagnostic pulse amplitude (4)	Base pulse = VCM; High level pulse = VCM+5%VREF		165		mV
<b>VCM_DIAG<sub>NEG</sub></b>	Negative Diagnostic pulse amplitude (4)	Base pulse = VCM; High level pulse = VCM-5%VREF		165		mV
<b>VCM_DIAG<sub>acc</sub></b>	Diagnostics Pulse accuracy (4)			0.1		%
<b>VCM_DIAG<sub>tr</sub></b>	Diagnostics Pulse rise time (4)	10% to 90% C=15pF		10		us
<b>VCM_DIAG<sub>tf</sub></b>	Diagnostics Pulse fall time (4)	90% to 10% C=15pF		10		us

- (1) Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that  $T_J = T_A$ . No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where  $T_J > T_A$ .
- (2) Limits are 100% production tested at  $25^{\circ}\text{C}$ . Limits over the operating temperature range are guaranteed through correlations using the Statistical Quality Control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.
- (4) This parameter is guaranteed by design and/or characterization and is not tested in production.

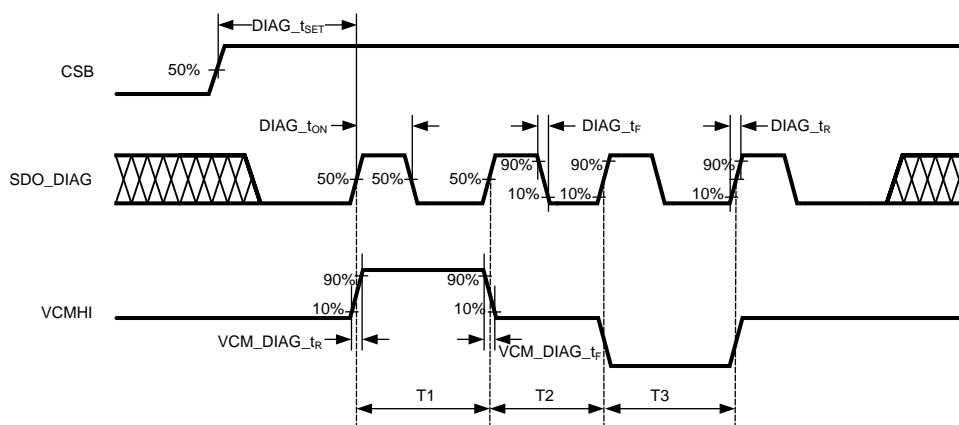
## Test Circuit Diagrams



## TEST CIRCUIT DIAGRAMS



**Figure 2. SERIAL INTERFACE TIMING DIAGRAM**

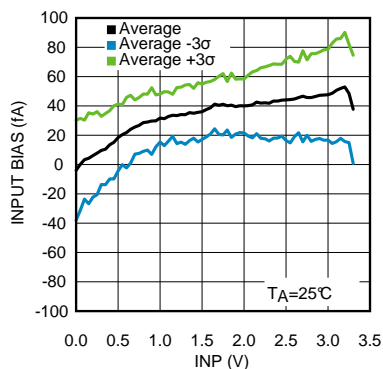


**Figure 3. DIAGNOSTIC TIMING DIAGRAM**

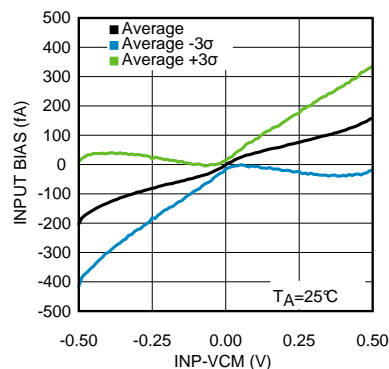
## Typical Performance Characteristics

Unless otherwise specified,  $T_A = 25^\circ\text{C}$ ,  $V_S = (V_{DD} - GND) = 3.3\text{V}$ ,  $V_{REF} = 3.3\text{V}$ .

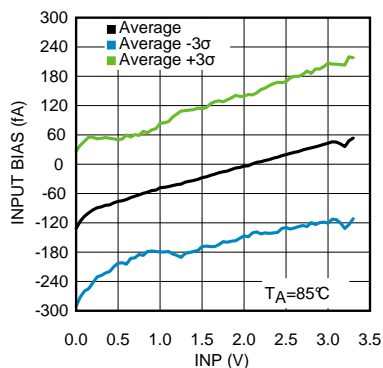
**pH Buffer Input Bias Current  
vs.  
 $V_{INP}$  - Device ON**



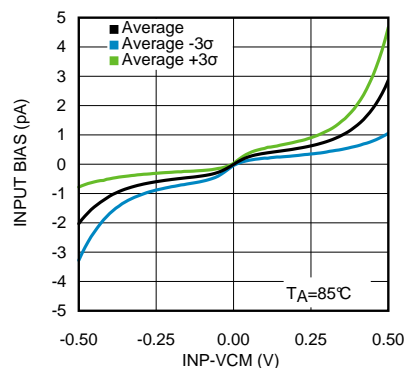
**pH Buffer Input Bias Current  
vs.  
 $V_{INP}$  - Device OFF**



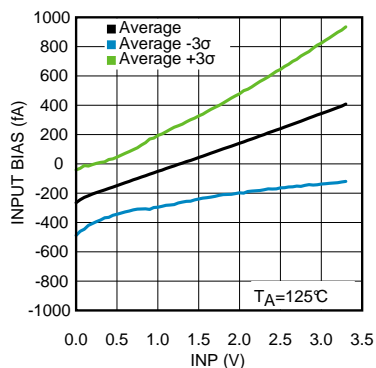
**pH Buffer Input Bias Current  
vs.  
 $V_{INP}$  - Device ON**



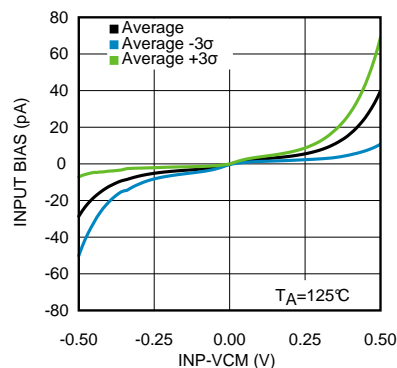
**pH Buffer Input Bias Current  
vs.  
 $V_{INP}$  - Device OFF**



**pH Buffer Input Bias Current  
vs.  
 $V_{INP}$  - Device ON**



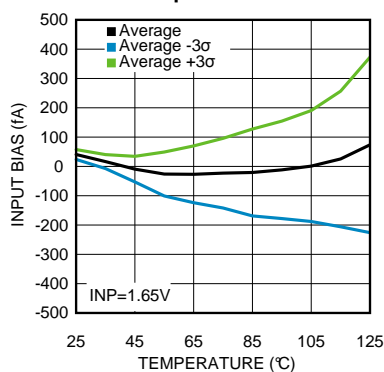
**pH Buffer Input Bias Current  
vs.  
 $V_{INP}$  - Device OFF**



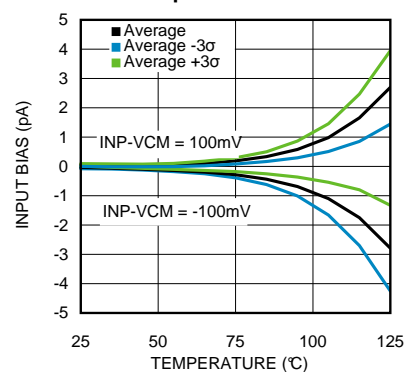
## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A = 25^\circ\text{C}$ ,  $V_S = (V_{DD} - GND) = 3.3\text{V}$ ,  $V_{REF} = 3.3\text{V}$ .

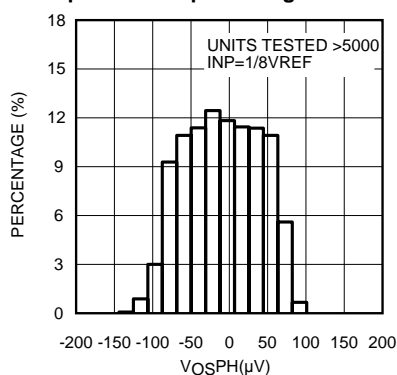
**pH Buffer Input Bias Current  
vs.  
Temp - Device ON**



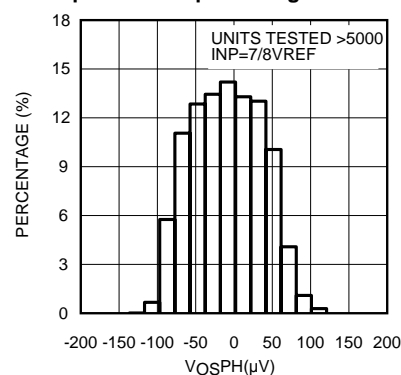
**pH Buffer Input Bias Current  
vs.  
Temp - Device OFF**



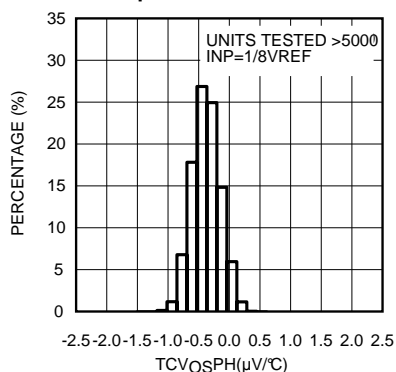
**pH Buffer Input Voltage Offset**



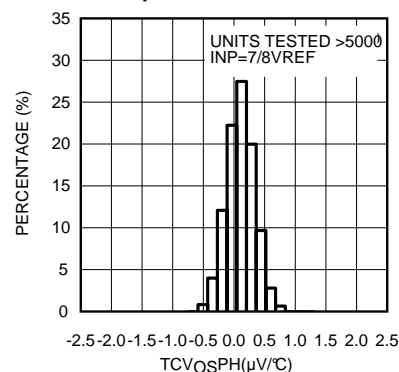
**pH Buffer Input Voltage Offset**



**pH Buffer TcVos**



**pH Buffer TcVos**



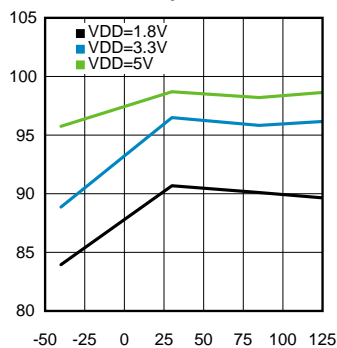
## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A=25^{\circ}\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ ,  $V_{REF}=3.3\text{V}$ .

**pH Buffer DC CMRR**

vs.

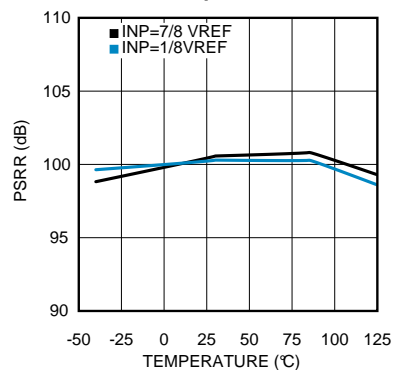
**Temperature**



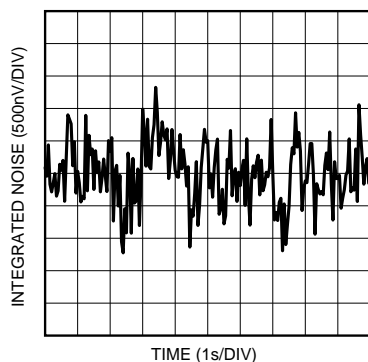
**pH Buffer DC PSRR**

vs.

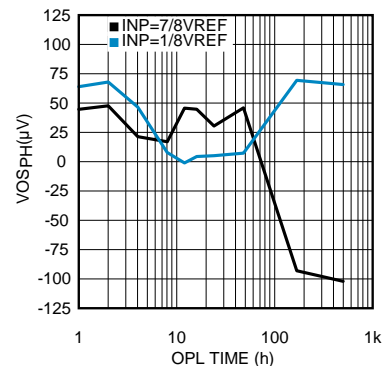
**Temperature**



**pH Buffer Time domain Voltage Noise**



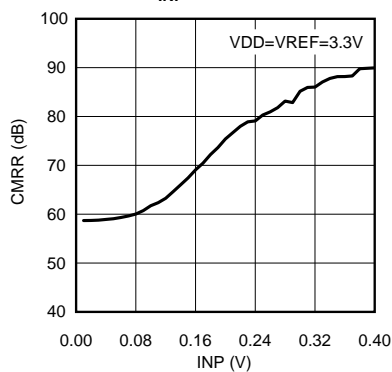
**pH Buffer Input Offset Voltage Drift**



**pH Buffer CMRR**

vs.

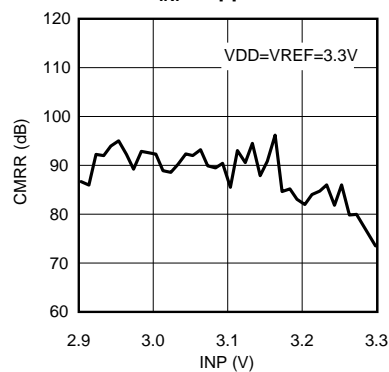
**V<sub>INP</sub> - lower rail**



**pH Buffer CMRR**

vs.

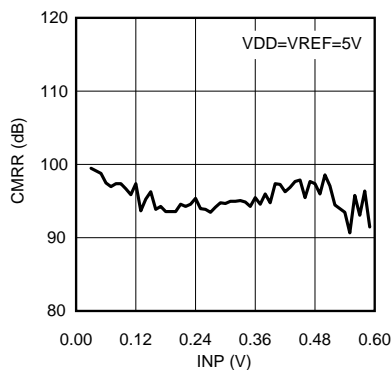
**V<sub>INP</sub> - upper rail**



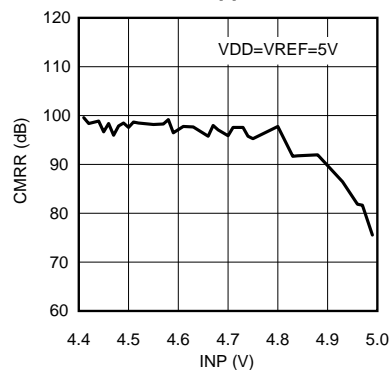
## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A=25^\circ\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ ,  $V_{REF}=3.3\text{V}$ .

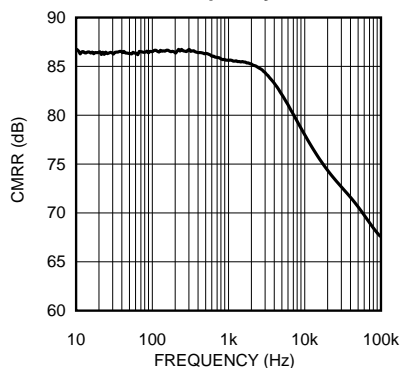
**pH Buffer CMRR  
vs.  
 $V_{INP}$  - lower rail**



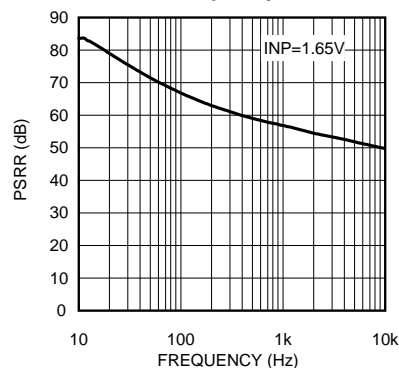
**pH Buffer CMRR  
vs.  
 $V_{INP}$  - upper rail**



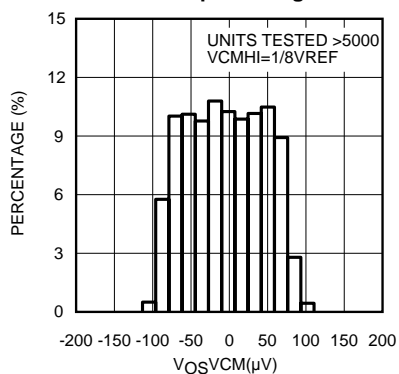
**pH Buffer CMRR  
vs.  
Frequency**



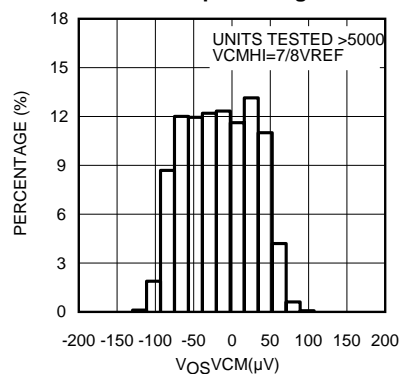
**pH Buffer PSRR  
vs.  
Frequency**



**VCM Buffer Input Voltage Offset**



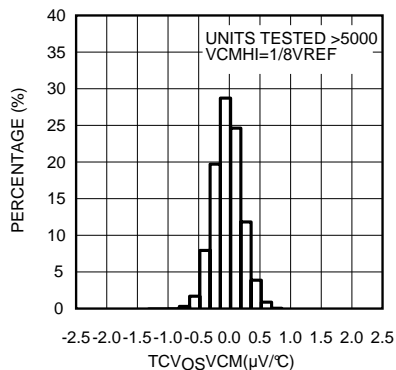
**VCM Buffer Input Voltage Offset**



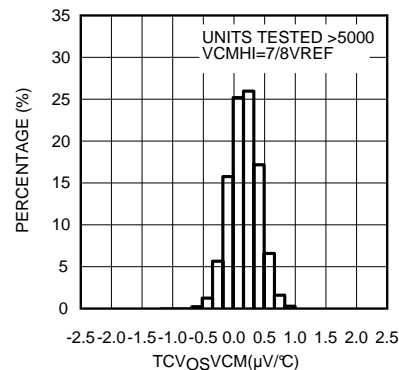
## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A=25^\circ\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ ,  $V_{REF}=3.3\text{V}$ .

**VCM Buffer TcVos**



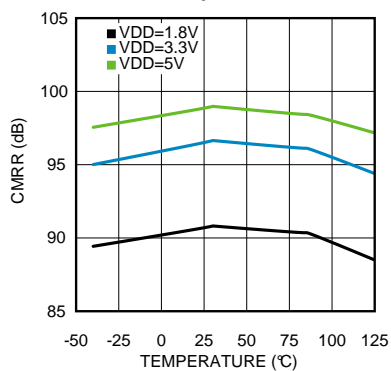
**VCM Buffer TcVos**



**VCM Buffer DC CMRR**

vs.

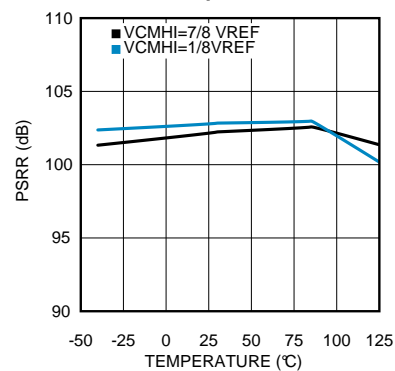
**Temperature**



**VCM Buffer DC PSRR**

vs.

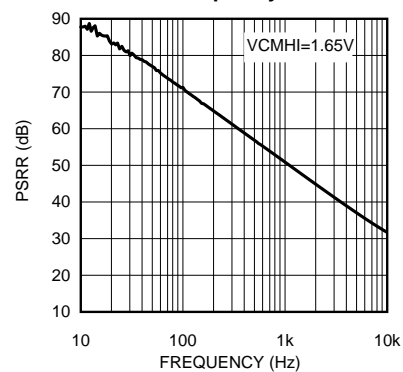
**Temperature**



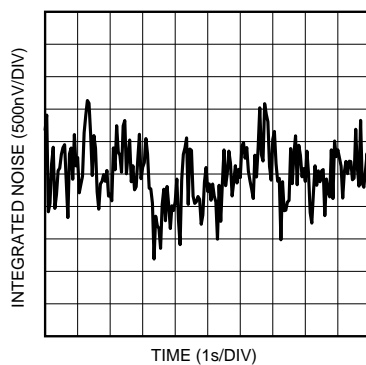
**VCM Buffer PSRR**

vs.

**Frequency**

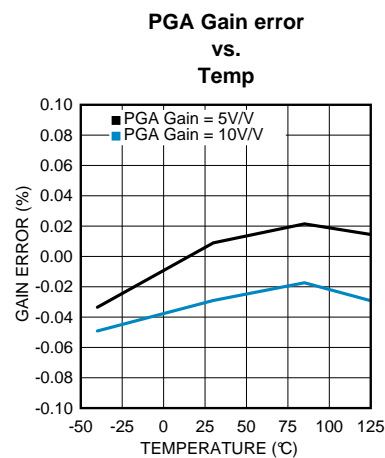
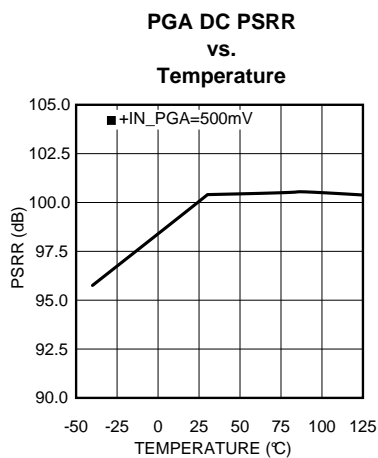
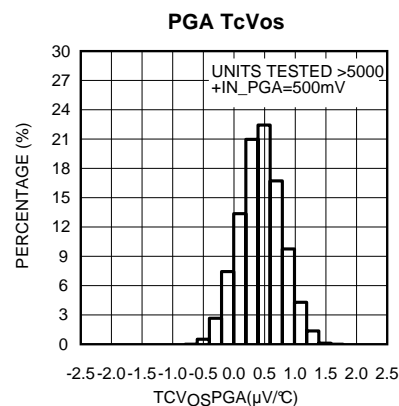
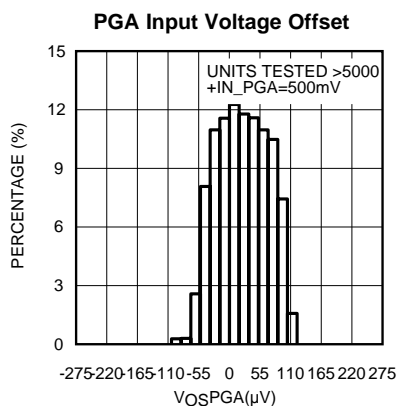
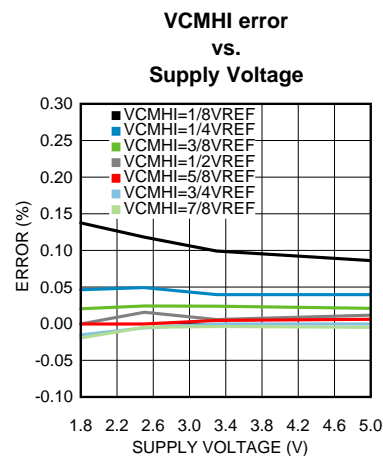
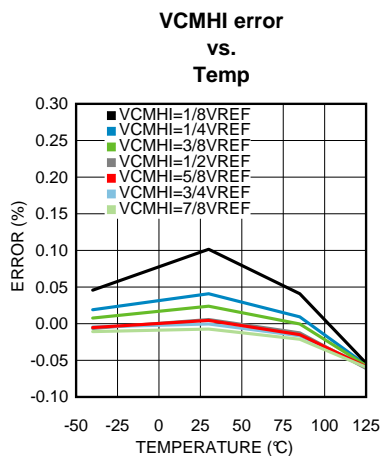


**VCM Buffer Time domain Voltage Noise**



## Typical Performance Characteristics (continued)

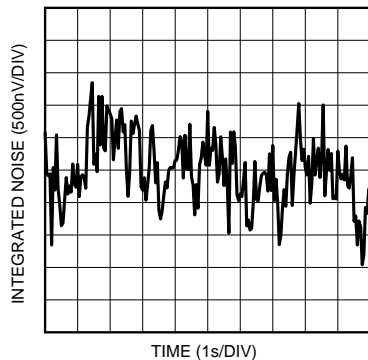
Unless otherwise specified,  $T_A = 25^\circ\text{C}$ ,  $V_S = (V_{DD} - GND) = 3.3\text{V}$ ,  $V_{REF} = 3.3\text{V}$ .



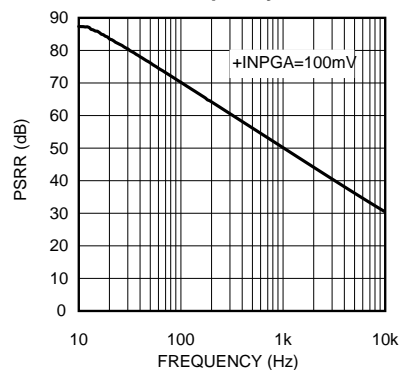
## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A=25^{\circ}\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ ,  $V_{REF}=3.3\text{V}$ .

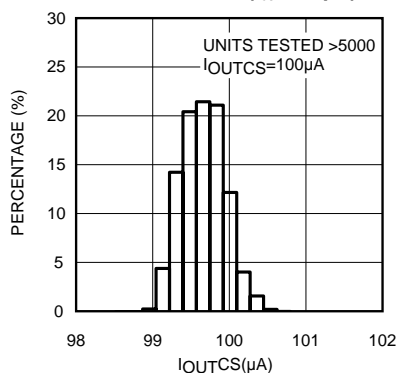
**PGA Time domain Voltage Noise**



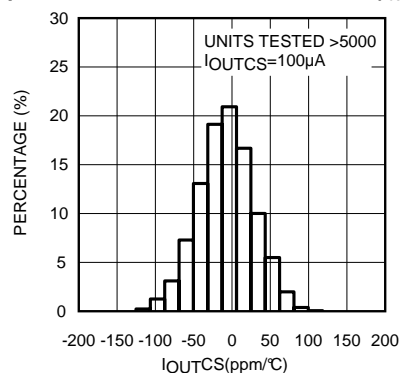
**PGA PSRR  
vs.  
Frequency**



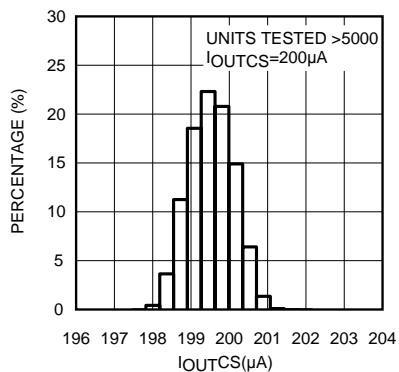
**Current Source ( $I_{CS}=100\mu\text{A}$ )**



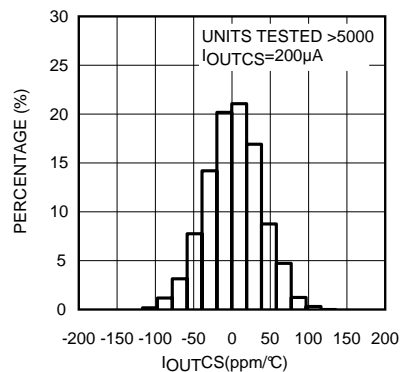
**Temperature coefficient Current Source ( $I_{CS}=100\mu\text{A}$ )**



**Current Source ( $I_{CS}=200\mu\text{A}$ )**



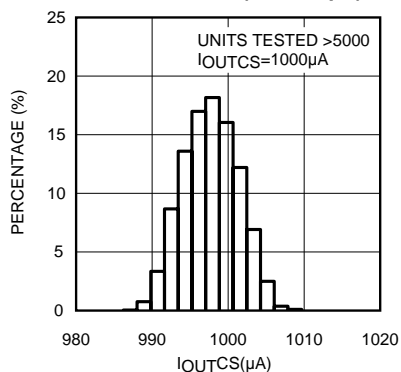
**Temperature coefficient Current Source ( $I_{CS}=200\mu\text{A}$ )**



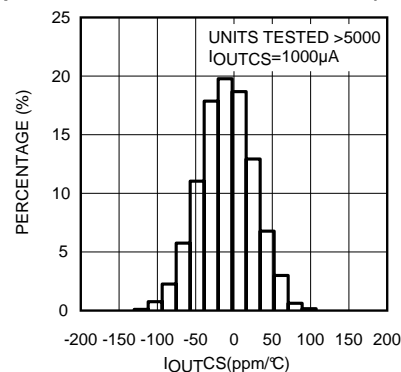
## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A = 25^\circ\text{C}$ ,  $V_S = (V_{DD} - GND) = 3.3\text{V}$ ,  $V_{REF} = 3.3\text{V}$ .

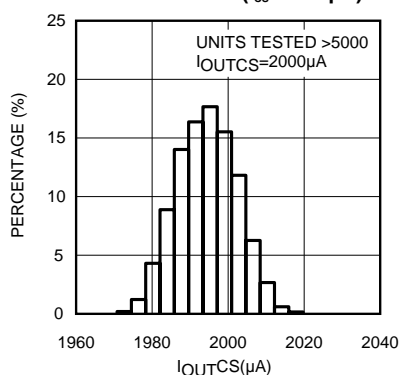
**Current Source ( $I_{CS} = 1000\mu\text{A}$ )**



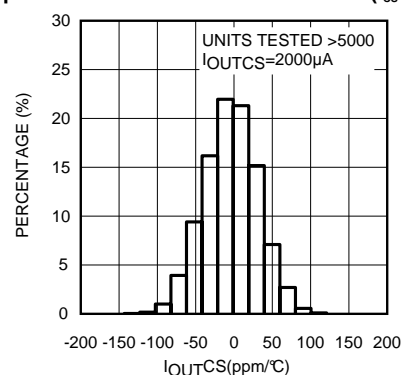
**Temperature coefficient Current Source ( $I_{CS} = 1000\mu\text{A}$ )**



**Current Source ( $I_{CS} = 2000\mu\text{A}$ )**

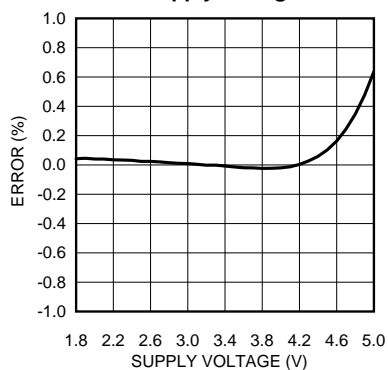


**Temperature coefficient Current Source ( $I_{CS} = 2000\mu\text{A}$ )**



**Current Source accuracy ( $I_{accCS}$ )  
vs.**

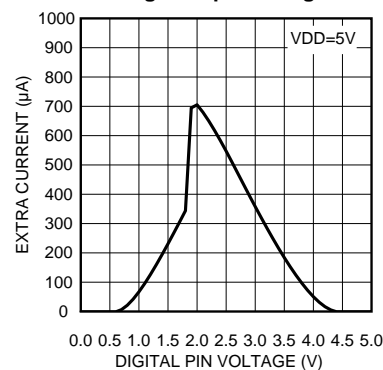
**Supply Voltage**



**Supply current**

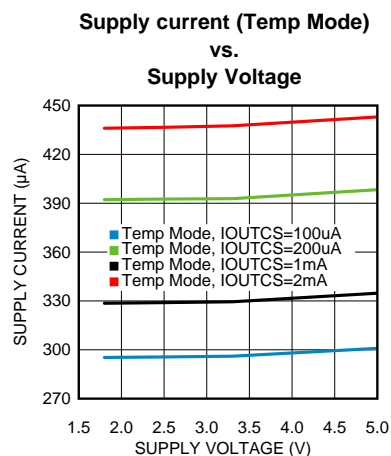
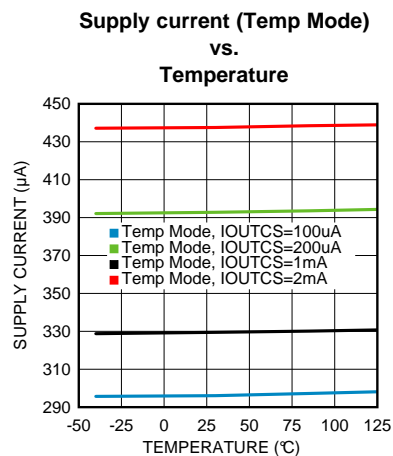
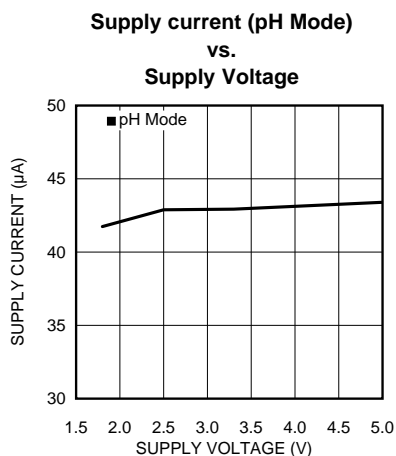
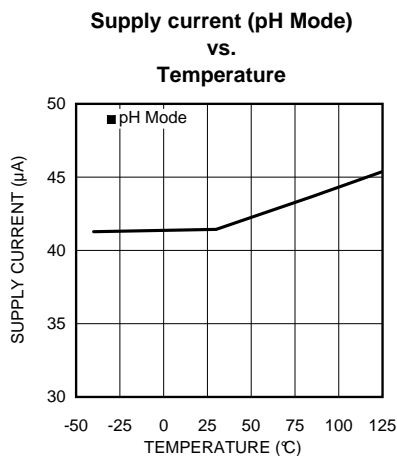
**vs.**

**digital input voltage**



## Typical Performance Characteristics (continued)

Unless otherwise specified,  $T_A=25^{\circ}\text{C}$ ,  $V_S=(V_{DD}-GND)=3.3\text{V}$ ,  $V_{REF}=3.3\text{V}$ .



## Functional Description

### GENERAL INFORMATION

The LMP91200 is a configurable sensor AFE for use in low power analytical sensing applications. The LMP91200 is designed for 2-electrode sensors. This device provides all of the functionality needed to detect changes based on a delta voltage at the sensor. Optimized for low-power applications, the LMP91200 works over a voltage range of 1.8V to 5.5V. With its extremely low input bias current it is optimized for use with pH sensors. Also in absence of supply voltage the very low input bias current reduces degradation of the pH probe when connected to the LMP91200. The Common Mode Output pin (VOCM) provides a common mode offset, which can be programmed to different values to accommodate pH sensor output ranges. For applications requiring a high impedance common mode this option is also available. Two guard pins provide support for high parasitic impedance wiring. Support for an external Pt1000, Pt100, or similar temperature sensor is integrated in the LMP91200. The control of this feature is available through the SPI interface. Additionally, a user controlled sensor diagnostic test is available. This function tests the sensor for proper connection and functionality.

### pH Buffer

The pH Buffer is a unity gain buffer with a input bias current in the range of tens fA at room. Its very low bias current introduces a negligible error in the measurement of the pH. The pH buffer is provided with 2 guard pins (GUARD1, GUARD2) in order to minimize the leakage of the input current and to make easy the design of a guard ring.

### Common mode selector and VCM buffer

The common mode selector allows to set 7 different values of common mode voltage (from 1/8 VREF to 7/8VREF with 1/8 VREF step) according to the applied voltage reference at VREF pin. Both buffered and unbuffered version of the set common mode voltage are available respectively at VCM pin and VCMHI pin. A copy of the buffered version is present at VOCM pin in case of differential measurement.

### Current Source and PGA

The internal current source is programmable current generator which is able to source 4 different current values (100µA, 200µA, 1mA, 2mA) in order to well stimulate Pt100 and Pt1000 thermal resistor. The selected current is sourced from either RTD pin (pin for thermal resistor connection) or CAL pin (pin for reference resistor connection). The voltage across either the thermal resistor or the reference resistor is amplified by the PGA (5V/V, 10V/V) and provided at the VOUT pin when the LMP91200 is set in Temperature measurement mode.

### Output Muxes

The output of the LMP91200 can be configured to support both differential and single ended ADC's. When measuring pH the Output signal can be referred either to VCM or GND. When measuring temperature the Output signal is referred to GND. The Output configuration is controlled through the SPI interface.

## SERIAL CONTROL INTERFACE OPERATION

All the features of the LMP91200 (Mode of Operation, PGA Gain, Voltage reference, Diagnostic) are by data stored in a programming register. Data to be written into the control register is first loaded into the LMP91200 via the serial interface. The serial interface employs a 16-bit shift register. Data is loaded through the serial data input, SDI. Data passing through the shift register is output through the serial data output, SDO\_DIAG. The serial clock, SCK controls the serial loading process. All sixteen data bits are required to correctly program the LMP91200. The falling edge of CSB enables the shift register to receive data. The SCK signal must be high during the falling and rising edge of CSB. Each data bit is clocked into the shift register on the rising edge of SCLK. Data is transferred from the shift register to the holding register on the rising edge of CSB.

**Table 1. Configuration Register**

Bit	Name	Description
D15	MEAS_MODE	<b>0 pH measurement (default)</b> <b>1 Temp measurement</b>
D14	I_MUX	<b>0 RTD (default)</b> <b>1 CAL</b>
[D13:D12]	I_VALUE	<b>00 100µA (default)</b> <b>01 200 µA</b> <b>10 1 mA</b> <b>11 2 mA</b>
D11	PGA	<b>0 5 V/V (default)</b> <b>1 10 V/V</b>
[D10 :D8]	VCM	<b>011 7/8Vref (default)</b> <b>010 3/4Vref</b> <b>001 5/8Vref</b> <b>000 1/2Vref</b> <b>100 1/2Vref</b> <b>101 3/8Vref</b> <b>110 1/4Vref</b> <b>111 1/8 Vref</b>
D7	VOCM	<b>0 VOCM (default)</b> <b>1 GND</b>
D6	DIAG_EN	<b>0 DIAG pin disabled (default)</b> <b>1 DIAG pin enabled</b>
[D5 :D0]	RESERVED	RESERVED

## Application Information

### Theory of pH measurement

pH electrode measurements are made by comparing the readings in a sample with the readings in standards whose pH has been defined (buffers). When a pH sensing electrode comes in contact with a sample, a potential develops across the sensing membrane surface and that membrane potential varies with pH. A reference electrode provides a second, unvarying potential to quantitatively compare the changes of the sensing membrane potential. Nowadays pH electrodes are composed of a sensing electrode with the reference electrode built into the same electrode body, they are called combination electrodes. A high input impedance meter serves as the readout device and calculates the difference between the reference electrode and sensing electrode potentials in millivolts. The millivolts are then converted to pH units according to the Nernst equation.

Electrode behavior is described by the Nernst equation:

$$E = E_o + (2.3 RT/nF) \log aH^+, \text{ where}$$

E is the measured potential from the sensing electrode,

E<sub>o</sub> is related to the potential of the reference electrode,

(2.3 RT/nF) is the Nernst factor,

log aH<sup>+</sup> is the pH, (aH<sup>+</sup> = activity of Hydrogen ions).

2.3 RT/nF, includes the Gas Law constant (R), Faraday's constant (F), the temperature in degrees Kelvin (T) and the stoichiometric number of ions involved in the process (n). For pH, where n = 1, the Nernst factor is 2.3 RT/F. Since R and F are constants, the factor and therefore electrode behavior is dependent on temperature. The Nernst Factor is equivalent to the electrode slope which is a measure of the electrode response to the ion being detected. When the temperature is 25 °C, the theoretical Nernst slope is 59.16 mV/pH unit.

### LMP91200 in pH meter with ATC (Automatic Temperature Compensation)

The most common cause of error in pH measurements is temperature. Temperature variations can influence pH for the following reasons:

the electrode slope will change with variations in temperature;

buffer and sample pH values will change with temperature.

Measurement drift can occur when the internal elements of the pH and reference electrodes are reaching thermal equilibrium after a temperature change. When the pH electrode and temperature probe are placed into a sample that varies significantly in temperature, the measurements can drift because the temperature response of the pH electrode and temperature probe may not be similar and the sample may not have a uniform temperature, so the pH electrode and temperature probe are responding to different environments.

The pH values of buffers and samples will change with variations in temperature because of their temperature dependent chemical equilibria. The pH electrode should be calibrated with buffers that have known pH values at different temperatures. Since pH meters are unable to correct sample pH values to a reference temperature, due to the unique pH versus temperature relationship of each sample, the calibration and measurements should be performed at the same temperature and sample pH values should be recorded with the sample temperature.

The LMP91200 offers in one package all the features to build a pH meter with ATC. Through the SPI Interface is possible to switch from pH measurement mode to temperature measurement mode and collect both temperature and potential of sensing electrode.

### pH measurement

The output of a pH electrode ranges from 415 mV to -415 mV as the pH changes from 0 to 14 at 25°C. The output impedance of a pH electrode is extremely high, ranging from 10 MΩ to 1000 MΩ. The low input bias current of the LMP91200 allows the voltage error produced by the input bias current and electrode resistance to be minimal. For example, the output impedance of the pH electrode used is 10 MΩ, if an op amp with 3 nA of I<sub>bias</sub> is used, the error caused due to this amplifier's input bias current and the source resistance of the pH electrode is 30 mV! This error can be greatly reduced to 1.25μV by using the LMP91200.

The pH measurement with the LMP91200 is straightforward, the pH electrode needs to be connected between VCM pin and INP pin. The voltage at VCM pin represent the internal zero of the system, so the potential of the electrode (voltage at INP pin) will be referred to VCM voltage. The common mode voltage can be set to well fit the input dynamic range of an external ADC connected between VOUT and VOCM when the LMP91200 is configured with differential output. In [Table 2](#) a typical configuration of the register of the LMP91200 with VCM set at 1/2 of VREF and differential output.

**Table 2. Configuration register: pH measurement**

Bit	Name	Description
D15	MEAS_MODE	0 pH measurement
D14	I_MUX	Leave these bits as they have been configured for the temperature measurement.
[D13:D12]	I_VALUE	
D11	PGA	
[D10 :D8]	VCM	000 1/2 VREF
D7	VOCM	0 VOCM
D6	DIAG_EN	0 DIAGNOSTIC disabled
[D5 :D0]	RESERVED	RESERVED

### Temperature measurement

The LMP91200 supports temperature measurement with RTD like Pt100 and Pt1000. According to the RTD connected to the LMP91200 the right amount of exciting current can be programmed: 100μA for Pt1000 and 1mA for Pt100, resulting in a nominal voltage drop of 100mV for both RTD's at 0°C. This voltage can be amplified, using an internal amplifier with a factor of 5 or 10 V/V. In case of high precision temperature measurement it is possible to connect an external high accuracy resistor and implement a calibration procedure. The exciting current sourced by the LMP91200 can be multiplexed either into the RTD or into the external precision resistor in order to implement a 2-step or 3-step temperature measurement. The multi step temperature measurements allows to remove uncertainty of the temperature signal path.

#### 1-step measurement

In the one step measurement the voltage across the RTD (Pt100, Pt1000) due to the exciting current is amplified and measured. The temperature can be calculated according to the following equation:

$$\text{Temp}(^{\circ}\text{C}) = (\text{Pt}_{\text{RES\_calculated}} - \text{Pt}_{\text{RES\_nominal}})/\alpha \quad (1)$$

where

**alpha** is the thermal coefficient of the RTD (it depends on the selected Ptres);

**Pt<sub>RES\_nominal</sub>** is the value of the Ptres at 0degC.

$$\text{Pt}_{\text{RES\_calculated}} = (\text{VOUT\_Pt}_{\text{RES}}/\text{I\_Pt})/\text{PGA\_GAIN} \quad (2)$$

where

**VOUT\_Pt<sub>RES</sub>** is the amplified voltage across the RTD at VOUT pin (ground referred) when the LMP91200 is configured according to [Table 3](#).

**I\_Pt** is the value of the selected exciting current according to the RTD;

**PGA\_GAIN** is the selected gain of the PGA.

Inserting [Equation 2](#) in [Equation 1](#) the temperature is given by the following equation:

$$\text{Temp}(^{\circ}\text{C}) = \text{Temp}(^{\circ}\text{C}) = ((\text{VOUT\_Pt}_{\text{RES}}/\text{I\_Pt})/\text{PGA\_GAIN} - \text{Pt}_{\text{RES\_nominal}})/\alpha \quad (3)$$

**Table 3. Configuration register: 1-step measurement**

Bit	Name	Description
D15	MEAS_MODE	1 Temp measurement
D14	I_MUX	0 RTD
[D13:D12]	I_VALUE	00 100μA (Pt1000) 10 1 mA (Pt100)

**Table 3. Configuration register: 1-step measurement (continued)**

D11	PGA	1 10 V/V
[D10 :D8]	VCM	Leave these bits as they have been configured for the pH measurement.
D7	VOCM	1 GND
D6	DIAG_EN	0 DIAGNOSTIC disabled
[D5 :D0]	RESERVED	RESERVED

The 1-step temperature measurement has a precision of about  $\pm 3^{\circ}\text{C}$ .

### 2-step measurement

This method requires 2 acquisitions and a precision resistor ( $R_{\text{REF}}$ ) connected between CAL and GND pin, (the RTD is always connected between RTD and GND pin). The first acquisitions measure the voltage across the precision resistor in the same condition (source current and PGA gain) of the next temperature measurement in order to remove the uncertainty on the current source value. The second acquisition measures the voltage across the RTD (similar to the 1-step measure), in this case the formula to calculate the temperature is a little bit more complicate in order to take in account the non-ideality of the system (source current error).

$$\text{Temp} (^{\circ}\text{C}) = (\text{Pt}_{\text{RES\_calculated}} - \text{Pt}_{\text{RES\_nominal}}) / \alpha \quad (4)$$

where

**alpha** is the thermal coefficient of the RTD (it depends on the selected Ptres);

**Ptres\_nominal** is the value of the Ptres at 0degC.

$$\text{Pt}_{\text{RES\_calculated}} = (\text{VOUT\_Pt}_{\text{RES}} / \text{PGA\_GAIN}) / \text{I\_true} \quad (5)$$

where

**VOUT\_Pt<sub>RES</sub>** is the amplified voltage across the RTD at VOUT pin (ground referred), when the LMP91200 is configured according to [Table 5](#).

**I<sub>true</sub>** is the real current which alternatively flows in the external precision resistance  $R_{\text{REF}}$  and in the RTD.

**PGA\_GAIN** is the selected gain of the PGA.

$$\text{I\_true} = (\text{VOUT\_R}_{\text{REF}}) / (\text{PGA\_GAIN} * \text{R}_{\text{REF}}) \quad (6)$$

where

**VOUT\_R<sub>REF</sub>** is the amplified voltage across the  $R_{\text{REF}}$  at VOUT pin (ground referred), when the LMP91200 is configured according to [Table 4](#).

Inserting [Equation 5](#) and [Equation 6](#) in [Equation 4](#) the temperature is given by the following equation:

$$\text{Temp} (^{\circ}\text{C}) = ((\text{VOUT\_Pt}_{\text{RES}} / \text{VOUT\_R}_{\text{REF}}) * \text{R}_{\text{REF}} - \text{Pt}_{\text{RES\_nominal}}) / \alpha \quad (7)$$

**Table 4.**

Bit	Name	Description
D15	MEAS_MODE	1 Temp measurement
D14	I_MUX	1 RCAL
[D13:D12]	I_VALUE	00 100μA (Pt1000) 10 1 mA (Pt100)
D11	PGA	1 10 V/V
[D10 :D8]	VCM	Leave these bits as they have been configured for the pH measurement.
D7	VOCM	1 GND
D6	DIAG_EN	0 DIAGNOSTIC disabled
[D5 :D0]	RESERVED	RESERVED

**Table 5. Configuration register: 2-step measurement**

Bit	Name	Description
D15	MEAS_MODE	1 Temp measurement
D14	I_MUX	0 RTD
[D13:D12]	I_VALUE	00 100μA (Pt1000) 10 1 mA (Pt100)
D11	PGA	1 10 V/V
[D10 :D8]	VCM	Leave these bits as they have been configured for the pH measurement.
D7	VOCM	1 GND
D6	DIAG_EN	0 DIAGNOSTIC disabled
[D5 :D0]	RESERVED	RESERVED

The 2-step temperature measurement has a precision of about  $\pm 0.3^{\circ}\text{C}$  (with  $R_{\text{REF}}$  @ 0.01% of tolerance) which is good enough in most of pH meter applications.

### 3-step measurement

This method requires 3 acquisitions and a precision resistor ( $R_{\text{REF}}$ ) connected between CAL and GND pin, (the RTD is always connected between RTD and GND pin). The first two acquisitions measure the voltage across the precision resistor in 2 different conditions (2 different exciting current and 2 PGA gains) in order to remove the uncertainty of the current source value and the offset of the path. The third acquisition measures the voltage across the RTD (similar to the 1-step measure), in this case the formula to calculate the temperature is more complicate in order to take in account the non-ideality of the system (offset, source current error).

$$\text{Temp}(^{\circ}\text{C}) = (\text{Pt}_{\text{RES\_calculated}} - \text{Pt}_{\text{RES\_nominal}}) / \alpha \quad (8)$$

where

**alpha** is the thermal coefficient of the RTD (it depends on the selected Ptres);

**Ptres\_nominal** is the value of the Ptres at 0degC.

$$\text{Pt}_{\text{RES\_calculated}} = ((\text{VOUT\_Pt}_{\text{RES}} / \text{PGA\_GAIN}) - \text{Vos}) / \text{I\_true} \quad (9)$$

where

**VOUT\_Pt<sub>RES</sub>** is the amplified voltage across the RTD at VOUT pin (ground referred), when the LMP91200 is configured according to [Table 8](#).

**I\_true** is the real current which alternatively flows in the external precision resistance  $R_{\text{REF}}$  and in the RTD.

**PGA\_GAIN** is the selected gain of the PGA.

**Vos** is the offset of the path.

$$\text{Vos} = (\text{VOUT\_R}_{\text{REF0}} - \text{VOUT\_R}_{\text{REF1}}) / 5 \quad (10)$$

where

**VOUT\_R<sub>REF0</sub>** is the amplified voltage across the  $R_{\text{REF}}$  at VOUT pin (ground referred), when the LMP91200 is configured according to [Table 6](#).

**VOUT\_R<sub>REF1</sub>** is the amplified voltage across the  $R_{\text{REF}}$  at VOUT pin (ground referred), when the LMP91200 is configured according to [Table 7](#).

$$\text{I\_true} = (2 * \text{VOUT\_R}_{\text{REF1}} - \text{VOUT\_R}_{\text{REF0}}) / (10 * R_{\text{REF}}) \quad (11)$$

Inserting [Equation 9](#), [Equation 10](#) and [Equation 11](#) in [Equation 8](#) the temperature is given by the following equation:

$$\text{Temp}(^{\circ}\text{C}) = (((\text{VOUT\_Pt}_{\text{RES}} / \text{PGA\_GAIN}) - (\text{VOUT\_R}_{\text{REF0}} - \text{VOUT\_R}_{\text{REF1}}) / 5) / ((2 * \text{VOUT\_R}_{\text{REF1}} - \text{VOUT\_R}_{\text{REF0}}) / (10 * R_{\text{REF}})) - \text{Pt}_{\text{RES\_nominal}}) / \alpha \quad (12)$$

**Table 6.**

Bit	Name	Description
D15	MEAS_MODE	1 Temp measurement

**Table 6. (continued)**

D14	I_MUX	1	RCAL	
[D13:D12]	I_VALUE	01 200μA 11 2	mA	(Pt1000) (Pt100)
D11	PGA	0	5 V/V	
[D10 :D8]	VCM	Leave these bits as they have been configured for the pH measurement.		
D7	VOCM	1	GND	
D6	DIAG_EN	0	DIAGNOSTIC disabled	
[D5 :D0]	RESERVED	RESERVED		

**Table 7.**

Bit	Name	Description		
D15	MEAS_MODE	1	Temp measurement	
D14	I_MUX	1	RCAL	
[D13:D12]	I_VALUE	00 100μA 10 1	mA	(Pt1000) (Pt100)
D11	PGA	1	10 V/V	
[D10 :D8]	VCM	Leave these bits as they have been configured for the pH measurement.		
D7	VOCM	1	GND	
D6	DIAG_EN	0	DIAGNOSTIC disabled	
[D5 :D0]	RESERVED	RESERVED		

**Table 8. Configuration register: 3-step measurement**

Bit	Name	Description		
D15	MEAS_MODE	1	Temp measurement	
D14	I_MUX	0	RTD	
[D13:D12]	I_VALUE	00 100μA 10 1	mA	(Pt1000) (Pt100)
D11	PGA	1	10 V/V	
[D10 :D8]	VCM	Leave these bits as they have been configured for the pH measurement.		
D7	VOCM	1	GND	
D6	DIAG_EN	0	DIAGNOSTIC disabled	
[D5 :D0]	RESERVED	RESERVED		

The 3-step temperature measurement can reach a precision as high as  $\pm 0.1^{\circ}\text{C}$  (with  $R_{\text{REF}}$  @ 0.01% of tolerance) when the analog signal is acquired by at least 16 bit ADC. With lower number of bit ADC this method gives the same result of the 2-step measurement due to the low voltage offset of the signal path. As rule of thumb, the 3-step temperature measurement gives good result if the LSB of the ADC is less than the input offset of the PGA.

### Diagnostic Feature

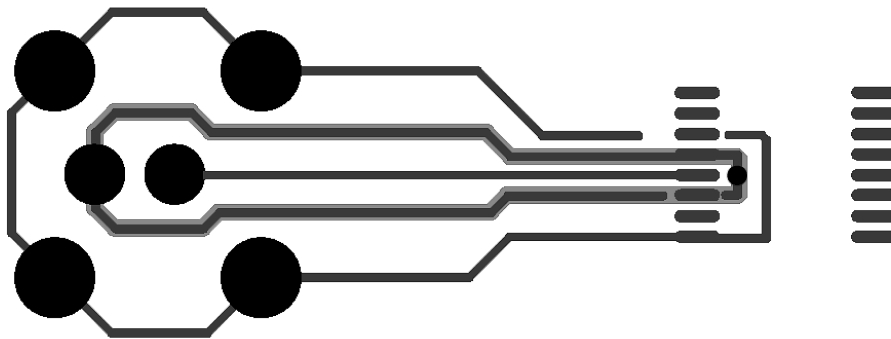
The diagnostic function allows detecting the presence of the sensor and checking the connection of the sensor. A further analysis of the answer of the pH probe to the diagnostic stimulus allows estimating the aging of the pH probe. With the diagnostic function is possible to change slightly (+/- 5% VREF) the Common mode voltage. If the sensor is present it reacts, this reaction gives some information on the status of the connection, the presence of the sensor and its aging. In fact a typical symptom of the aging of a pH probe is the slowness in the answer. It means that a pH probe answers with a smoother step to the diagnostic stimulus as its age increases.

The procedure is enabled and disabled by SPI (refer to [Table 1](#)). Until bit D6 is at low logic level, VCM stays at the programmed voltage independently by the SDO\_DIAG pin status. When bit D6 is tied at high logic level, on the first rising edge of SDO\_DIAG, a positive pulse is generated. At the second positive rising edge of SDO\_DIAG pin, the positive pulse ends. At the third positive rising edge of SDO\_DIAG a negative pulse is generated. At the fourth positive rising edge of the SDO\_DIAG the negative pulse ends and the routine is stopped and cannot restart until bit D6 is set again at 1.

### Layout Consideration

In pH measurement, due to the high impedance of the pH Electrode, careful circuit layout and assembly are required. Guarding techniques are highly recommended to reduce parasitic leakage current by isolating the LMP91200's input from large voltage gradients across the PCB. A guard is a low impedance conductor that surrounds an input line and its potential is raised to the input line's voltage. The input pin should be fully guarded as shown in [Figure 4](#). The guard traces should completely encircle the input connections. In addition, they should be located on both sides of the PCB and be connected together. The LMP91200 makes the guard ring easy to be implemented without any other external op amp. The ring needs to be connected to the guard pins (GUARD1 and GUARD2) which are at the same potential of the INP pin. Solder mask should not cover the input and the guard area including guard traces on either side of the PCB. Sockets are not recommended as they can be a significant leakage source. After assembly, a thorough cleaning using commercial solvent is necessary.

In [Figure 4](#) is showed a typical guard ring circuit when the LMP912000 is interfaced to a pH probe through a triaxial cable/connector, usually known as 'TRIAx'. The signal conductor and the guard of the triax should be kept at the same potential; therefore, the leakage current between them is practically zero. Since triax has an extra layer of insulation and a second conducting sheath, it offers greater rejection of interference than coaxial cable/connector.



**Figure 4. Circuit Board Guard Layout**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LMP91200MT/NOPB	ACTIVE	TSSOP	PW	16	92	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	
LMP91200MTX/NOPB	ACTIVE	TSSOP	PW	16	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

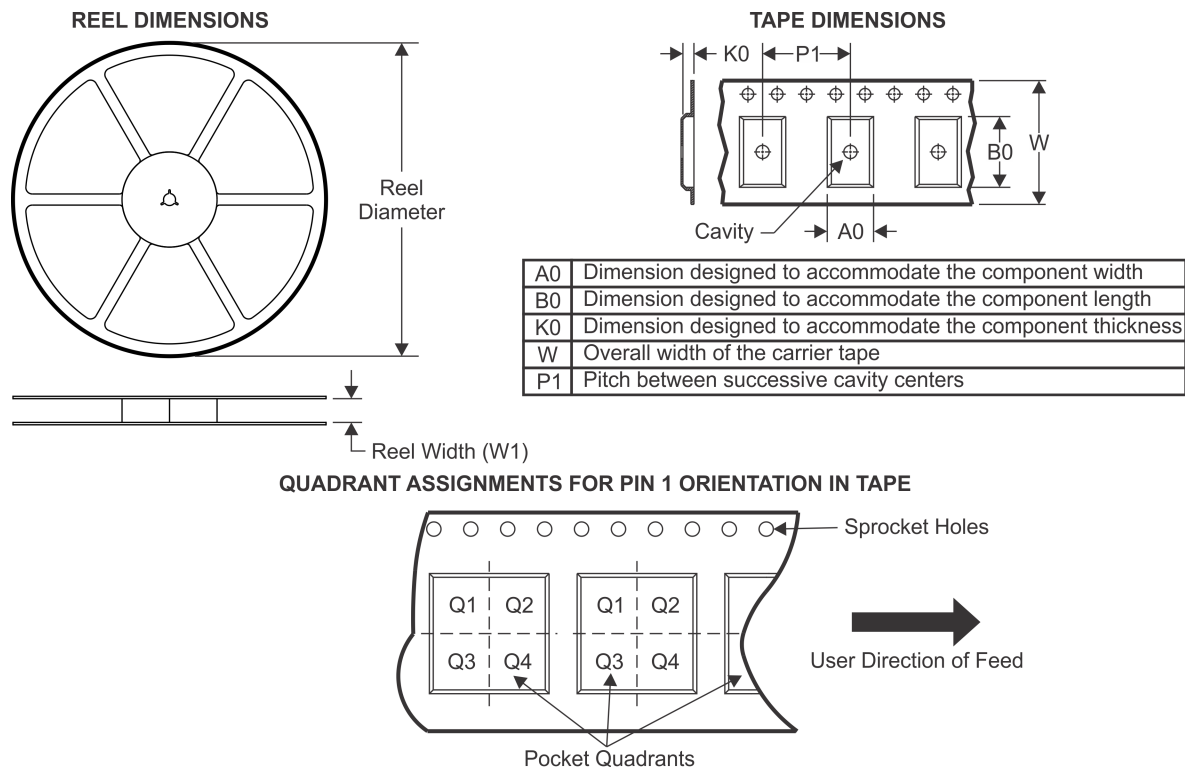
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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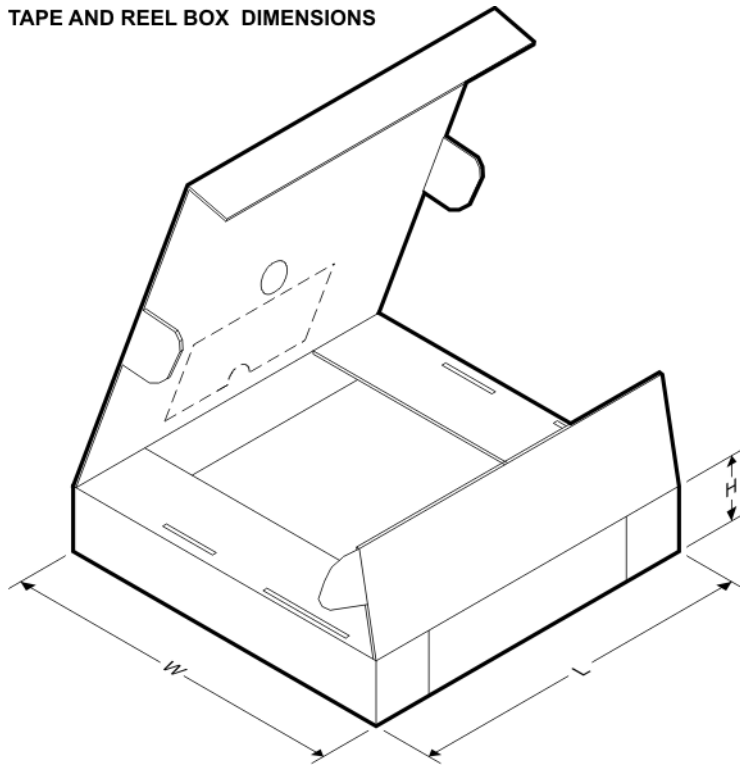
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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMP91200MTX/NOPB	TSSOP	PW	16	2500	330.0	12.4	6.95	8.3	1.6	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS

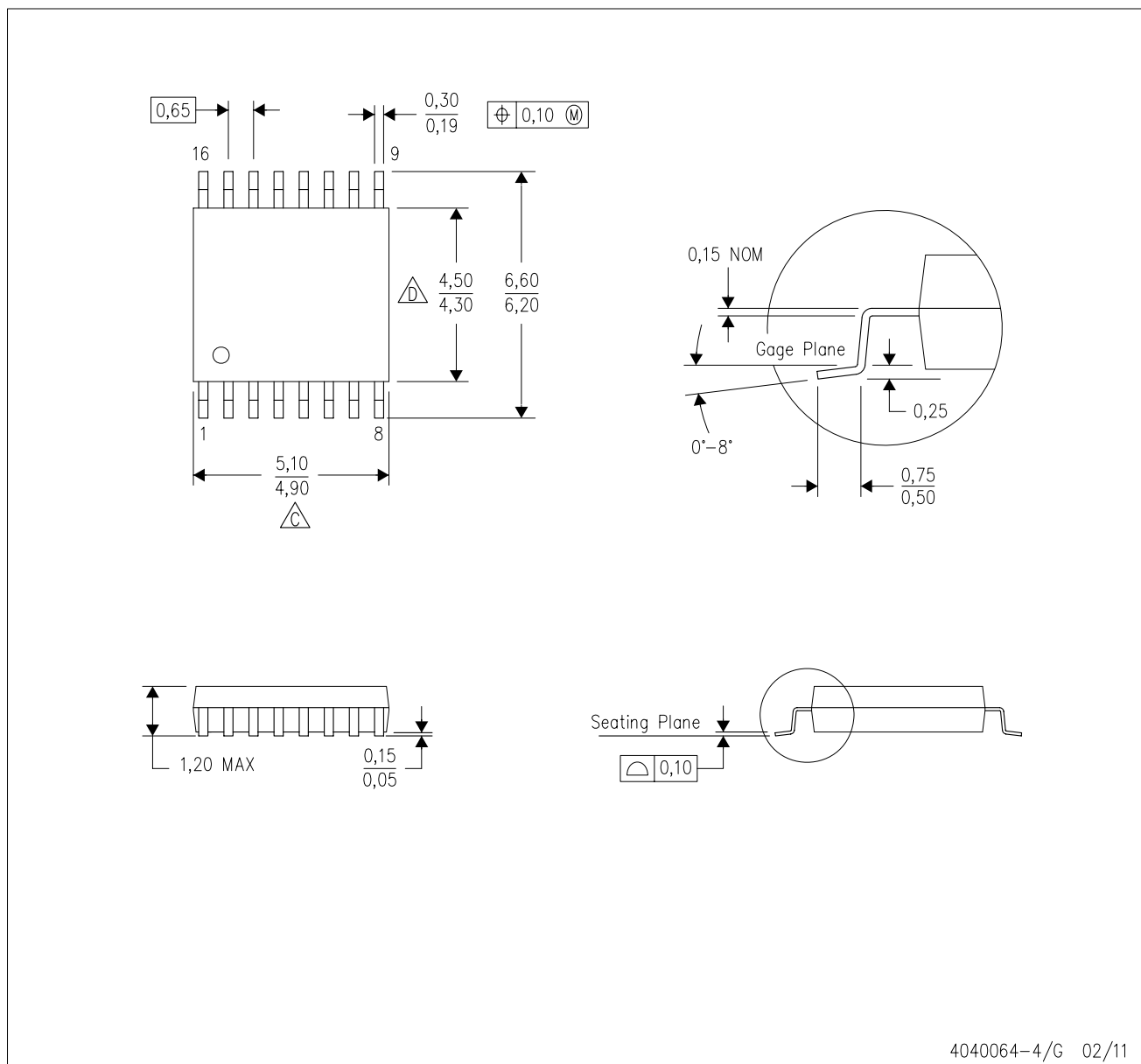


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMP91200MTX/NOPB	TSSOP	PW	16	2500	358.0	343.0	63.0

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

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